

#### IEC QUALITY ASSESSMENT SYSTEM (IECQ)

## covering Electronic Components, Assemblies, Related Materials and Processes

For rules and details of the IECQ visit www.iecq.org

## Schedule of Scope to Certificate of Approval

### **Independent Testing Laboratory**

IECQ Certificate No.: IECQ-L DEKRA 17.0001
CB Certificate No.: DEKRA-C10A

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# 1. Environmental and Reliability Testing of Electronic Components, Assemblies, and Related Materials

Description test	Standard	Remarks
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA, including FIB (Focused Ion Beam), SEM (Scanning electron microscope)	MIL-STD-883 Method 2018.4 JESD22A121 JESD201	Or customer specified test
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA, includes Electrical Analysis and Physical Analysis with Sample Preparation (Decap, X-section, etc)	MIL-STD-883 Method 2009.9 IPC-A-610 IPC-A-600 MIL-STD-883 Method 2008.4 JESD22A121 JESD201 IPC-TM-650 2.1.1 IPC-6012	Or customer specified test
Failure and material analysis of semiconductor IC, electronic components and PCB/PCBA, includes NDE (Non-destructive Testing)	MIL-STD-883 Method 2012.7 J-STD-035 J-STD-020	Or customer specified test
Electrostatic discharge test. (Including: HBM / MM / CDM / Latch Up / ESD Gun )	JESD 47 JEDEC22-A114/A115/C101 EIA/JESD78 ANSI JEDEC ESDA JS001/JS002 AEC-Q100-002/003/004/011 AEC-Q101-001/002/005 AEC-Q200-002 JEITA ED4701 IEC61000-4-2 MIL-STD-883	Or customer specified test

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